

RF SWITCH CG2185X2

6GHz Medium Power SPDT Switch

DESCRIPTION

 The CG2185X2 is a pHEMT GaAs FET SPDT (Single Pole Double Throw) Switch. This device can operate from 2.0GHz to 6.0GHz, with low insertion loss and high isolation.

FEATURES

Control voltage:
 VC(H) = 1.8 to 5.0 V (3.0V TYP.)
 VC(L) = -0.2 to 0.2 V (0V TYP.)

Low insertion loss:

 $L_{ins}1 = 0.35 \text{ dB TYP.} @ f = 2.0 \text{ to } 2.5 \text{ GHz}$ $L_{ins}2 = 0.40 \text{ dB TYP.} @ f = 4.9 \text{ to } 6.0 \text{ GHz}$

High isolation :

ISL1 = 28 dB TYP. @ f = 2.0 to 2.5 GHz ISL2 = 26 dB TYP. @ f = 4.9 to 6.0 GHz

Power handling :

 $P_{in(1dB)}$ = +32 dBm TYP. @ VC(H) = 3.0 V, VC(L) = 0 V

PACKAGE

 6-pin plastic Thin Small SON (X2) Package (1.0mm x 1.0mm x 0.37mm)



APPLICATIONS

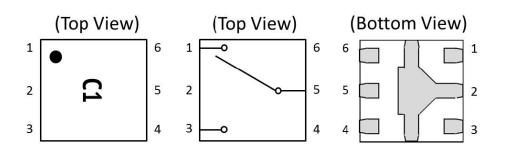
- Wireless LAN (IEEE802.11a/b/g/n/ac)
- ISM band radios

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Description
CG2185X2	CG2185X2-C2	6-pin plastic TSSON (XS02) (Pb-Free)	C1	 Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape MOQ 10 kpcs/reel
CG2185X2-EVAL	CG2185X2-EVAL			Evaluation Board with DC block capacitors, power supply bypass capacitors, and RF and DC connectors MOQ 1



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	VC2
5	RFC
6	VC1

Remark Exposed pad: GND

TRUTH TABLE

VC1	VC2	RFC-RF1	RFC-RF2
High	Low	OFF	ON
Low	High	ON	OFF

ABSOLUTE MAXIMUM RATINGS

(TA = +25°C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Control Voltage	VC	6.0 ^{Note 1}	V
Input Power	P _{in}	+33 ^{Note 2}	dBm
Operating Ambient Temperature	T _A	-45 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +150	°C

Note 1. |VC1 - VC2|≦6.0V

2. 3.0V≦|VC1 - VC2|≦5.0V

RECOMMENDED OPERATING RANGE

(TA = +25°C, unless otherwise specified)

(1/1 = 120 0; difficus otherwise specifica)						
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	
Operating Frequency	f	2.0	-	6.0	GHz	
Switch Control Voltage (H)	VC(H)	+1.8	+3.0	+5.0	V	
Switch Control Voltage (L)	VC(L)	-0.2	0	+0.2	V	



ELECTRICAL CHARACTERISTICS

(TA=+25°C, VC(H)=3.0V, VC(L)=0V, Zo=50Ω, DC Block Capacitance=8pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	Lins1	f = 2.0 to 2.5 GHz	-	0.35	0.55	dB
	Lins2	f = 4.9 to 6.0 GHz	-	0.40	0.60	dB
Isolation	ISL1	f = 2.0 to 2.5 GHz	25	28	-	dB
	ISL2	f = 4.9 to 6.0 GHz	23	26	-	dB
Input Return Loss	RL _{in} 1	f = 2.0 to 2.5 GHz	23	26	-	dB
	RL _{in} 2	f = 4.9 to 6.0 GHz	15	18	-	dB
Output Return Loss	RL _{out} 1	f = 2.0 to 2.5 GHz	21	24	-	dB
	RL _{out} 2	f = 4.9 to 6.0 GHz	15	18	-	dB
0.1 dB Loss Compression Input Power	P _{in(0.1 dB)}	f = 2.5 GHz, VC(H)=1.8V, VC(L)=0V	+20	+23	-	dBm
Note 1		f = 2.5 GHz, VC(H)=3.0V, VC(L)=0V	+26	+29	-	dBm
		f = 6.0 GHz, VC(H)=1.8V, VC(L)=0V	+19	+22	-	dBm
		f = 6.0 GHz VC(H)=3.0V, VC(L)=0V	+26	+29	-	dBm
1 dB Loss Compression Input Power	P _{in(1 dB)}	f = 2.5 GHz, VC(H)=1.8V, VC(L)=0V	+24	+27	-	dBm
Note 2		f = 2.5 GHz, VC(H)=3.0V, VC(L)=0V	+29	+32	-	dBm
		f = 6.0 GHz, VC(H)=1.8V, VC(L)=0V	+22	+25	-	dBm
		f = 6.0 GHz VC(H)=3.0V, VC(L)=0V	+29	+32	-	dBm
3rd Order Input Intercept Point	IIP3	f = 2.5GHz 2-tone 5MHz Spacing	-	+55	-	dBm
Error Vector Magnitude	EVM	802.11a, 64QAM, 54Mbps, Pin≦+24.5dBm	-	2.5	-	%
		802.11g, 64QAM, 54Mbps, Pin≦+25.5dBm	-	2.5	-	%
Switching Speed	t _{sw}	50% CTL to 90/10%	-	50	150	ns
Switch Control Current	I _{cont}	RF None	_	2	10	μA

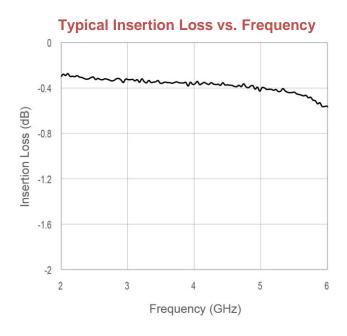
Note 1. P_{in(0.1dB)} is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

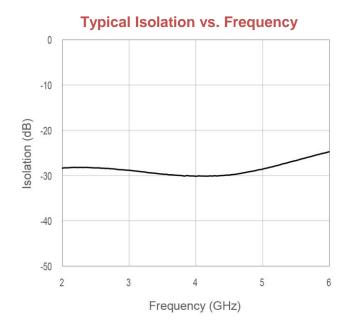
^{2.} P_{in(1dB)} is the measured input power level when the insertion loss increases 1dB more than that of the linear range.

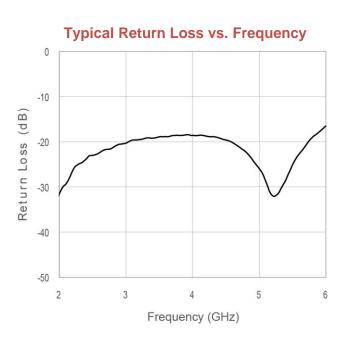


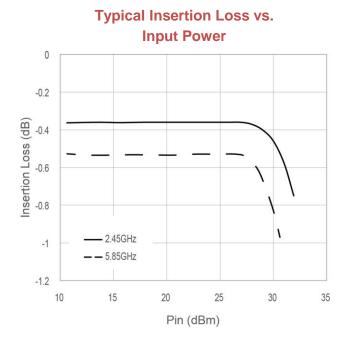
TYPICAL CHARACTERISTICS

 $(VC(H)=3V, VC(L)=0V, T_A=+25^{\circ}C, DC Block Capacitance=8pF, through board loss is subtracted in insertion loss data)$



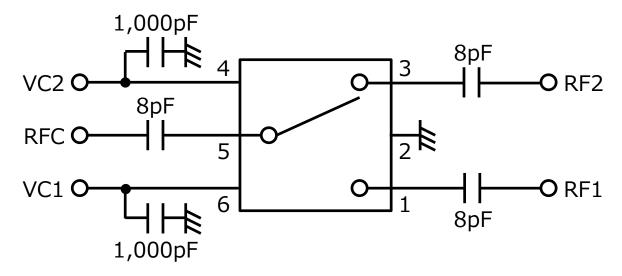








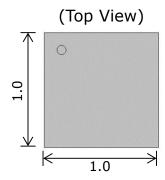
EVALUATION CIRCUIT

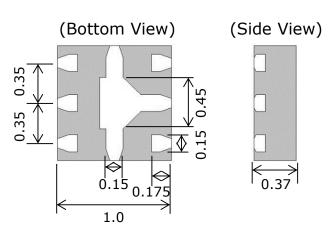


The application circuits and their parameters are for reference only and are not intended for use in actual designs. DC Blocking Capacitors are required at all RF ports.

PACKAGE DIMENSIONS

6-pin Plastic TSSON (XS02) (Unit: mm)







RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on the CEL's Part Summary page under Associated Documents



REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0004-02 (Issue A) February 17, 2016	Initial datasheet	N/A
CDS-0004-02 (Issue B) March 24, 2016	Added Eval Board ordering information. Updated Marking information.	Page 1,2
CDS-0004-02 (Issue C) August 11, 2016	Removed "preliminary"	All
CDS-0004-02 (Issue D) January 11, 2017	Added "Recommended Soldering Conditions" section	5
CDS-0004-03 (Issue E) June 21, 2017	Added Error Vector Magnitude parameter to Electrical Characteristics table	3
CDS-0004-04 (Issue F) August 29, 2017	Updated Applications section Added "Typical Characteristics" graph section	1, 4



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